

N-Channel 30V(D-S) Enhancement MOSFET

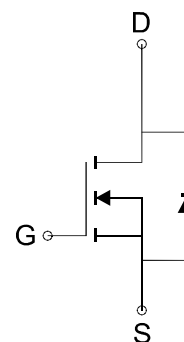
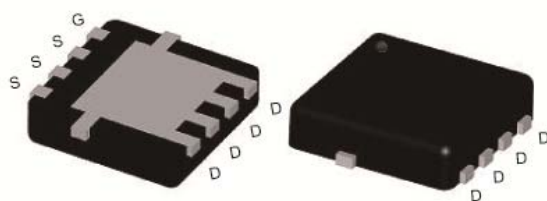
GENERAL DESCRIPTION

The ME7114S is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where Low-side switching , and low in-line power loss are needed in a very small outline surface mount package.

PIN CONFIGURATION

(DFN 3.3x3.3)

Top View



N-Channel MOSFET

FEATURES

- $R_{DS(ON)} \leq 7m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} \leq 10.5m\Omega @ V_{GS}=4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch

Ordering Information: ME7114S-G (Green product-Halogen free)

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Parameter		Symbol	Maximum Ratings				Unit
Drain-Source Voltage		V _{DS}	30				V
Gate-Source Voltage		V _{GS}	±20				V
Continuous Drain Current(T _j =150℃)*	T _C =25℃	I _D	71				A
	T _C =70℃		57				
	T _A =25℃		18.4				
	T _A =70℃		14.7				
Pulsed Drain Current		I _{DM}	74				A
Maximum Power Dissipation*	T _C =25℃	P _D	52				W
	T _C =70℃		33				
	T _A =25℃		3.8				
	T _A =70℃		2.4				
Operating Junction Temperature		T _J	-55 to 150				℃
Thermal Resistance-Junction to Ambient*		R _{θJA}	Typ	26	Max	33	℃/W
Thermal Resistance-Junction to Case*		R _{θJC}	Typ	1.9	Max	2.4	

*The device mounted on 1in² FR4 board with 2 oz copper

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Electrical Characteristics (TA=25°C Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	30			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250 μ A	1.0		3.0	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} = $\pm$ 20V			$\pm$ 100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V			1	μ A
R _{DS(ON)}	Drain-Source On-State Resistance ^a	V _{GS} =10V, I _D =13A		5.8	7	m Ω
		V _{GS} =4.5V, I _D =10A		8.5	10.5	
V _{SD}	Diode Forward Voltage	I _S =2.8A, V _{GS} =0V		0.75	1.1	V
DYNAMIC						
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _D =13A		37		nC
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _D =13A		18		
Q _{gs}	Gate-Source Charge			7.7		
Q _{gd}	Gate-Drain Charge			8.8		
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz		1690		pF
C _{oss}	Output Capacitance			260		
C _{rss}	Reverse Transfer Capacitance			84		
R _g	Gate-Resistance	V _{DS} =0V, V _{GS} =0V, F=1MHz		0.9		Ω
t _{d(on)}	Turn-On Delay Time	V _{DD} =15V, R _L =15 Ω I _D =1A, V _{GEN} =10V R _G =6 Ω		20		ns
t _r	Turn-On Rise Time			16		
t _{d(off)}	Turn-Off Delay Time			63		
t _f	Turn-Off Fall Time			11		

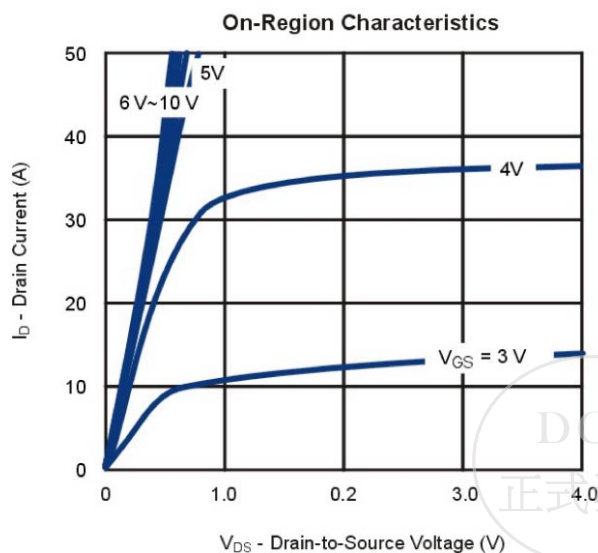
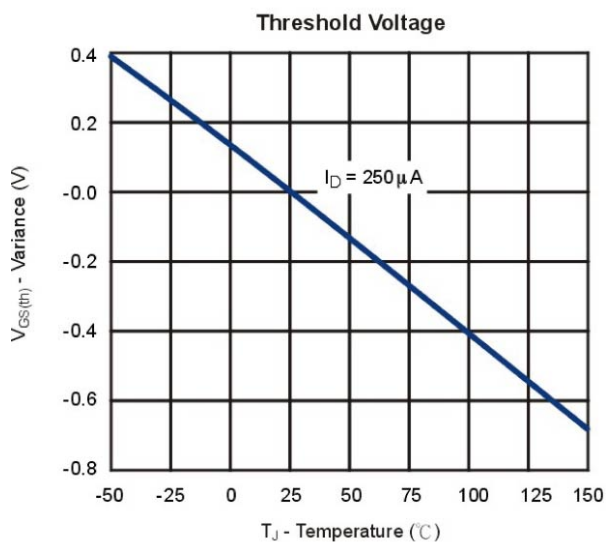
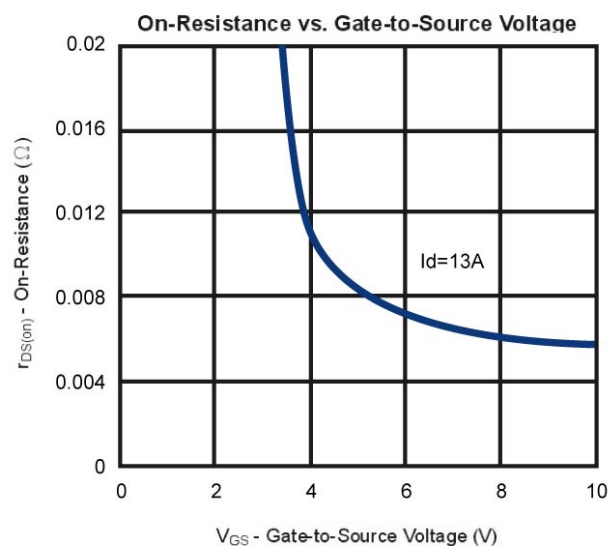
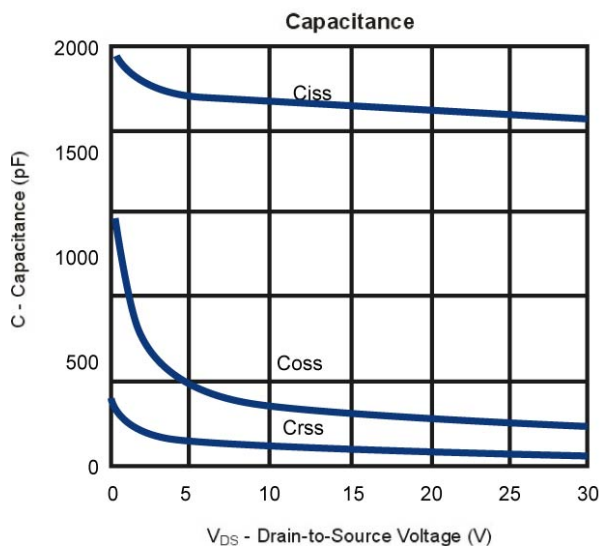
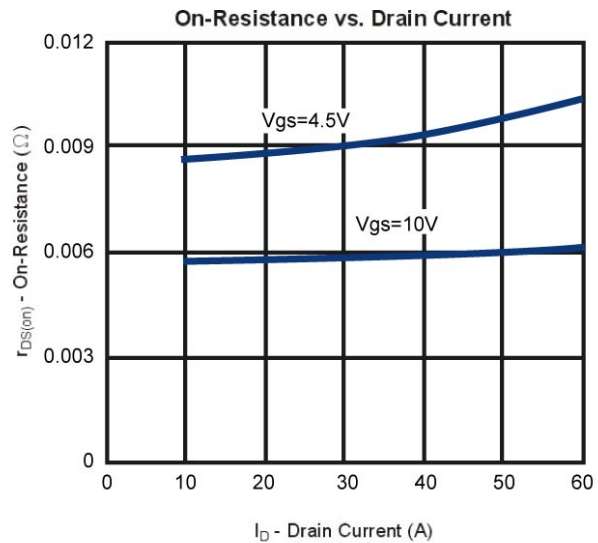
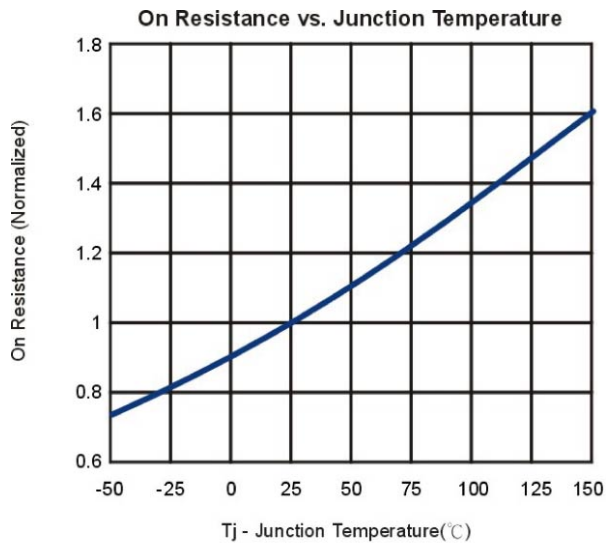
Note: a. Pulse test: pulse width $\leq$ 300 μ s, duty cycle $\leq$ 2%

b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.



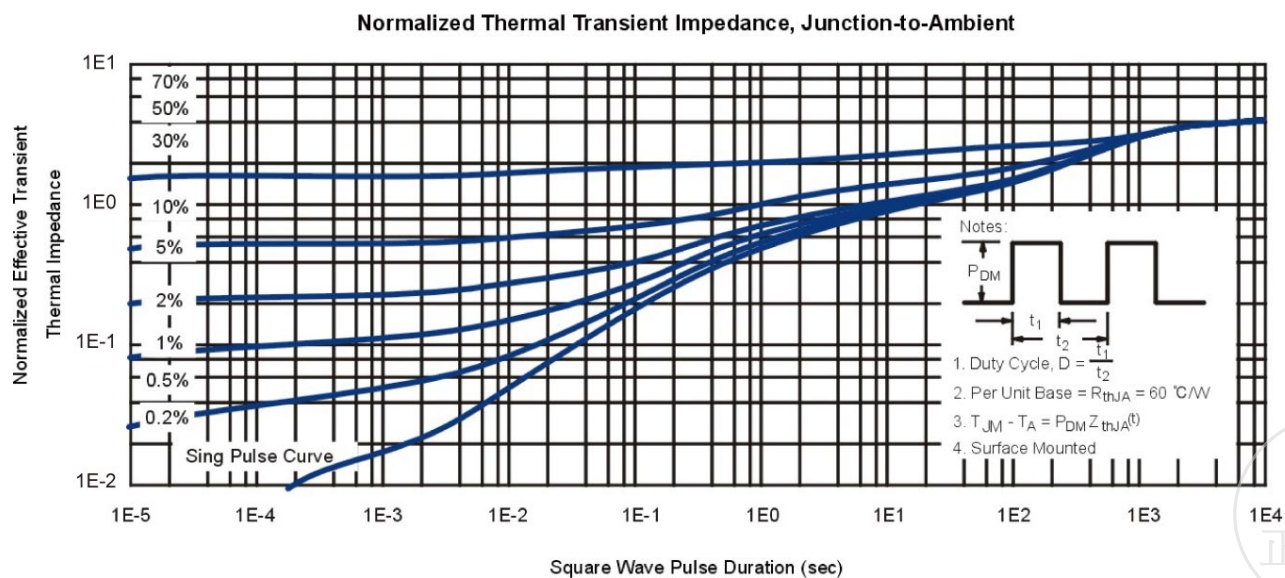
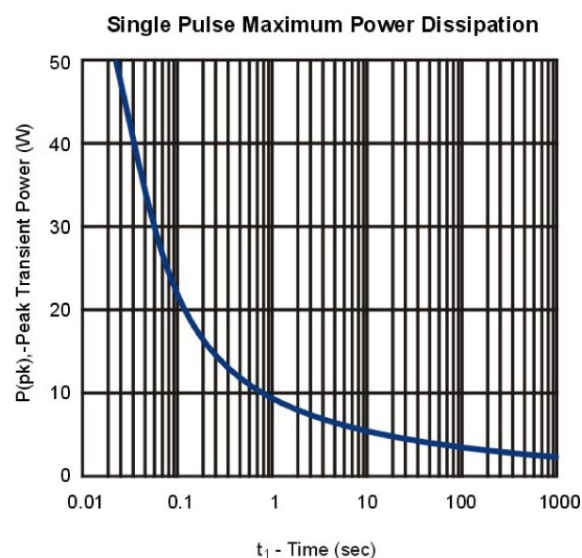
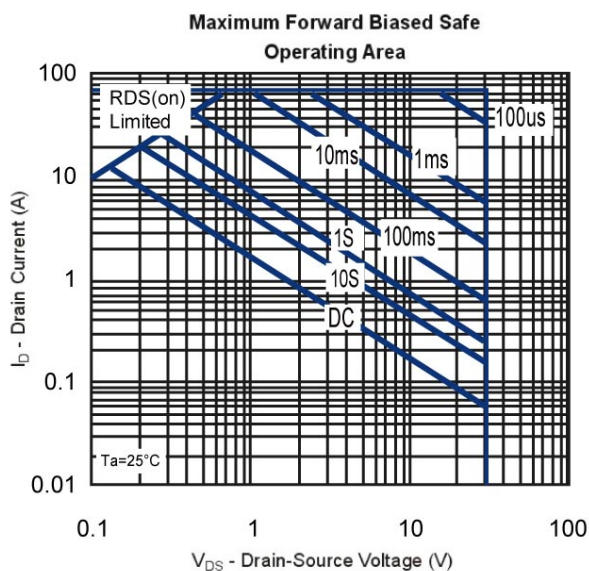
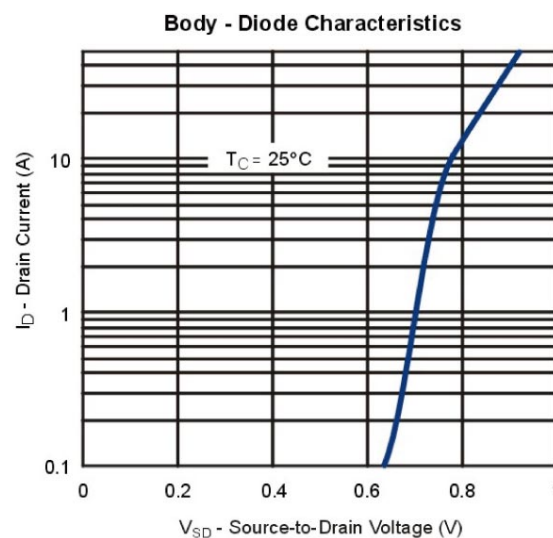
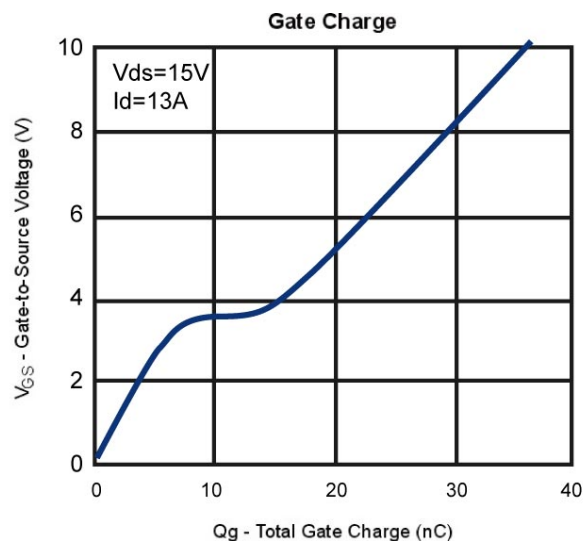
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Typical Characteristics (T_J = 25°C Noted)

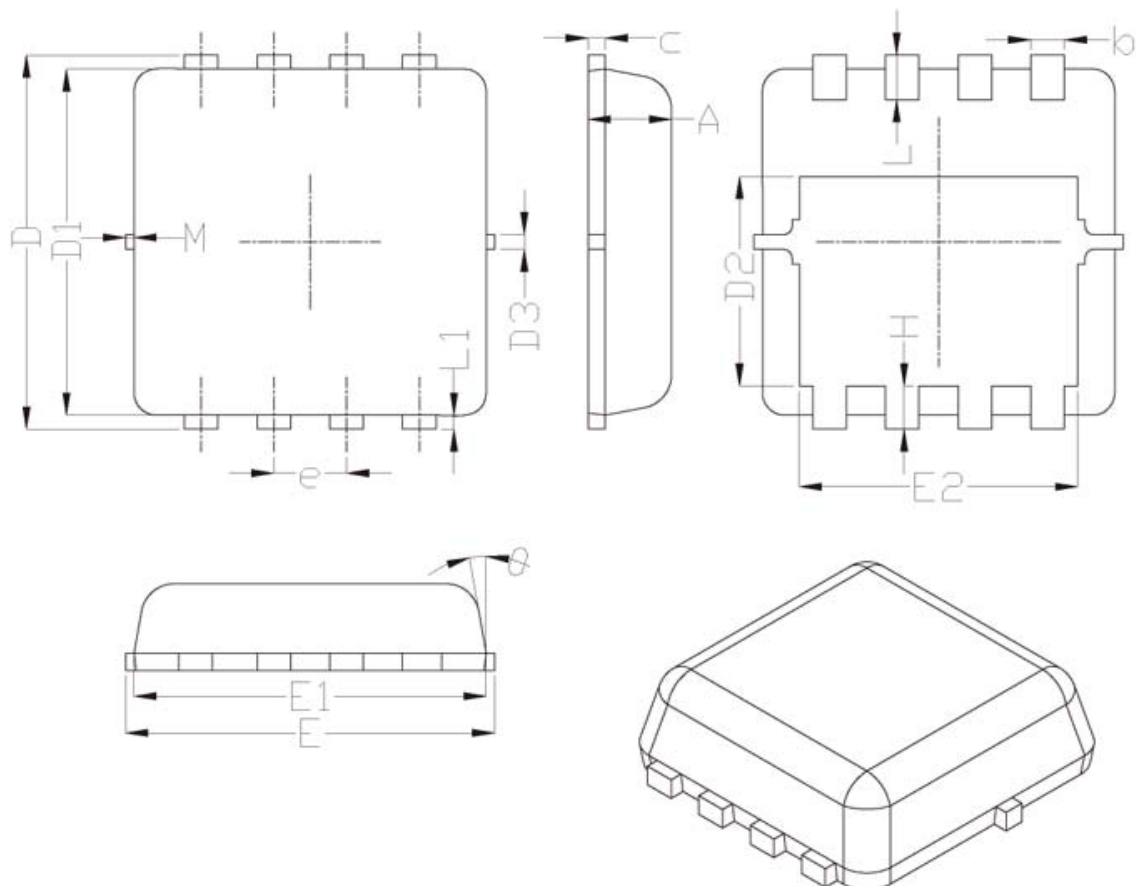


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DFN(S) 3.3x3.3 Package Outline



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
θ	---	10°	12°
M	*	*	0.15
* Not specified			

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